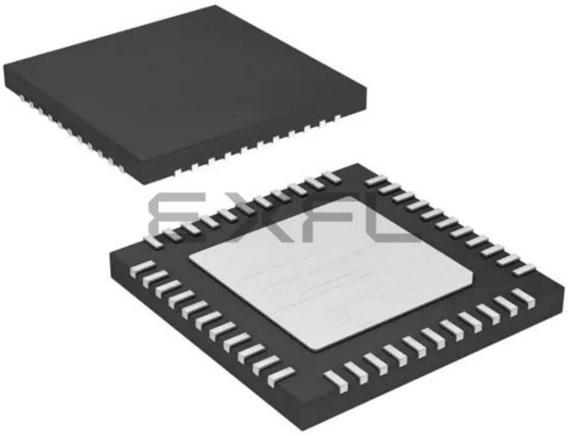

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx220f032dt-v-ml

NOTES:

Coprocessor 0 also contains the logic for identifying and managing exceptions. Exceptions can be caused by a variety of sources, including alignment errors in data, external events or program errors. Table 3-3 lists the exception types in order of priority.

TABLE 3-3: MIPS32® M4K® PROCESSOR CORE EXCEPTION TYPES

Exception	Description
Reset	Assertion $\overline{\text{MCLR}}$ or a Power-on Reset (POR).
DSS	EJTAG debug single step.
DINT	EJTAG debug interrupt. Caused by the assertion of the external *EJ_DINT* input or by setting the EjtagBrk bit in the ECR register.
NMI	Assertion of NMI signal.
Interrupt	Assertion of unmasked hardware or software interrupt signal.
DIB	EJTAG debug hardware instruction break matched.
AdEL	Fetch address alignment error. Fetch reference to protected address.
IBE	Instruction fetch bus error.
DBp	EJTAG breakpoint (execution of `SDBBP` instruction).
Sys	Execution of `SYSCALL` instruction.
Bp	Execution of `BREAK` instruction.
RI	Execution of a reserved instruction.
CpU	Execution of a coprocessor instruction for a coprocessor that is not enabled.
CEU	Execution of a `CorExtend` instruction when `CorExtend` is not enabled.
Ov	Execution of an arithmetic instruction that overflowed.
Tr	Execution of a trap (when trap condition is true).
DDBL/DDBS	EJTAG Data Address Break (address only) or EJTAG data value break on store (address + value).
AdEL	Load address alignment error. Load reference to protected address.
AdES	Store address alignment error. Store to protected address.
DBE	Load or store bus error.
DDBL	EJTAG data hardware breakpoint matched in load data compare.

3.3 Power Management

The MIPS M4K processor core offers many power management features, including low-power design, active power management and power-down modes of operation. The core is a static design that supports slowing or Halting the clocks, which reduces system power consumption during Idle periods.

3.3.1 INSTRUCTION-CONTROLLED POWER MANAGEMENT

The mechanism for invoking Power-Down mode is through execution of the `WAIT` instruction. For more information on power management, see **Section 26.0 “Power-Saving Features”**.

3.4 EJTAG Debug Support

The MIPS M4K processor core provides an Enhanced JTAG (EJTAG) interface for use in the software debug of application and kernel code. In addition to standard User mode and Kernel modes of operation, the M4K core provides a Debug mode that is entered after a debug exception (derived from a hardware breakpoint, single-step exception, etc.) is taken and continues until a Debug Exception Return (`DERET`) instruction is executed. During this time, the processor executes the debug exception handler routine.

The EJTAG interface operates through the Test Access Port (TAP), a serial communication port used for transferring test data in and out of the core. In addition to the standard JTAG instructions, special instructions defined in the EJTAG specification define which registers are selected and how they are used.

REGISTER 4-4: BMXDUPBA: DATA RAM USER PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUPBA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15-10 **BMXDUPBA<15:10>:** DRM User Program Base Address bits

When non-zero, the value selects the relative base address for User mode program space in RAM, BMXDUPBA must be greater than BMXDUDBA.

bit 9-0 **BMXDUPBA<9:0>:** Read-Only bits

This value is always ‘0’, which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

REGISTER 5-4: NVMDATA: FLASH PROGRAM DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-0 **NVMDATA<31:0>:** Flash Programming Data bits

Note: The bits in this register are only reset by a Power-on Reset (POR).

REGISTER 5-5: NVMSRCADDR: SOURCE DATA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-0 **NVMSRCADDR<31:0>:** Source Data Address bits

The system physical address of the data to be programmed into the Flash when the NVMOP<3:0> bits (NVMCON<3:0>) are set to perform row programming.

REGISTER 6-2: RSWRST: SOFTWARE RESET REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	W-0, HC
	—	—	—	—	—	—	—	SWRST[1]

Legend:	HC = Cleared by hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-1 **Unimplemented:** Read as ‘`0`’

bit 0 **SWRST:** Software Reset Trigger bit[1]

`1` = Enable Software Reset event
`0` = No effect

Note 1: The system unlock sequence must be performed before the SWRST bit is written. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Interrupt Source[1]	IRQ #	Vector #	Interrupt Bit Location				Persistent Interrupt
			Flag	Enable	Priority	Sub-priority	
U1E – UART1 Fault	39	32	IFS1<7>	IEC1<7>	IPC8<4:2>	IPC8<1:0>	Yes
U1RX – UART1 Receive Done	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>	Yes
U1TX – UART1 Transfer Done	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>	Yes
I2C1B – I2C1 Bus Collision Event	42	33	IFS1<10>	IEC1<10>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1S – I2C1 Slave Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1M – I2C1 Master Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>	Yes
CNA – PORTA Input Change Interrupt	45	34	IFS1<13>	IEC1<13>	IPC8<20:18>	IPC8<17:16>	Yes
CNB – PORTB Input Change Interrupt	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>	Yes
CNC – PORTC Input Change Interrupt	47	34	IFS1<15>	IEC1<15>	IPC8<20:18>	IPC8<17:16>	Yes
PMP – Parallel Master Port	48	35	IFS1<16>	IEC1<16>	IPC8<28:26>	IPC8<25:24>	Yes
PMPE – Parallel Master Port Error	49	35	IFS1<17>	IEC1<17>	IPC8<28:26>	IPC8<25:24>	Yes
SPI2E – SPI2 Fault	50	36	IFS1<18>	IEC1<18>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2RX – SPI2 Receive Done	51	36	IFS1<19>	IEC1<19>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2TX – SPI2 Transfer Done	52	36	IFS1<20>	IEC1<20>	IPC9<4:2>	IPC9<1:0>	Yes
U2E – UART2 Error	53	37	IFS1<21>	IEC1<21>	IPC9<12:10>	IPC9<9:8>	Yes
U2RX – UART2 Receiver	54	37	IFS1<22>	IEC1<22>	IPC9<12:10>	IPC9<9:8>	Yes
U2TX – UART2 Transmitter	55	37	IFS1<23>	IEC1<23>	IPC9<12:10>	IPC9<9:8>	Yes
I2C2B – I2C2 Bus Collision Event	56	38	IFS1<24>	IEC1<24>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2S – I2C2 Slave Event	57	38	IFS1<25>	IEC1<25>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2M – I2C2 Master Event	58	38	IFS1<26>	IEC1<26>	IPC9<20:18>	IPC9<17:16>	Yes
CTMU – CTMU Event	59	39	IFS1<27>	IEC1<27>	IPC9<28:26>	IPC9<25:24>	Yes
DMA0 – DMA Channel 0	60	40	IFS1<28>	IEC1<28>	IPC10<4:2>	IPC10<1:0>	No
DMA1 – DMA Channel 1	61	41	IFS1<29>	IEC1<29>	IPC10<12:10>	IPC10<9:8>	No
DMA2 – DMA Channel 2	62	42	IFS1<30>	IEC1<30>	IPC10<20:18>	IPC10<17:16>	No
DMA3 – DMA Channel 3	63	43	IFS1<31>	IEC1<31>	IPC10<28:26>	IPC10<25:24>	No
Lowest Natural Order Priority							

Note 1: Not all interrupt sources are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

REGISTER 8-4: REFOTRIM: REFERENCE OSCILLATOR TRIM REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ROTRIM<8:1>							
23:16	R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	ROTRIM<0>	—	—	—	—	—	—	—
15:8	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:
R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR
‘1’ = Bit is set
‘0’ = Bit is cleared
x = Bit is unknown

bit 31-23 **ROTRIM<8:0>:** Reference Oscillator Trim bits

`111111111` = 511/512 divisor added to RODIV value
`111111110` = 510/512 divisor added to RODIV value
•
•
•
`100000000` = 256/512 divisor added to RODIV value
•
•
•
`000000010` = 2/512 divisor added to RODIV value
`000000001` = 1/512 divisor added to RODIV value
`000000000` = 0/512 divisor added to RODIV value

bit 22-0 **Unimplemented:** Read as ‘`0`’

Note: While the ON (REFOCON<15>) bit is ‘`1`’, writes to this register do not take effect until the DIVSWEN bit is also set to ‘`1`’.

TABLE 9-3: DMA CHANNELS 0-3 REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name[1]	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCPTR<15:0>																0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHBUSY	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSSIZ<15:0>																0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDSIZ<15:0>																0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHSPTR<15:0>																0000
3260	DCH2DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHDPTR<15:0>																0000
3270	DCH2CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CHCSIZ<15:0>																0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 10-20: U1CNFG1: USB CONFIGURATION 1 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	U-0	R/W-0
	UTEYE	UOEMON	—	USBSIDL	—	—	—	UASUSPND

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘`0`’

bit 7 **UTEYE:** USB Eye-Pattern Test Enable bit

`1` = Eye-Pattern Test is enabled

`0` = Eye-Pattern Test is disabled

bit 6 **UOEMON:** USB $\overline{\text{OE}}$ Monitor Enable bit

`1` = OE signal is active; it indicates intervals during which the D+/D- lines are driving

`0` = OE signal is inactive

bit 5 **Unimplemented:** Read as ‘`0`’

bit 4 **USBSIDL:** Stop in Idle Mode bit

`1` = Discontinue module operation when the device enters Idle mode

`0` = Continue module operation when the device enters Idle mode

bit 3-1 **Unimplemented:** Read as ‘`0`’

bit 0 **UASUSPND:** Automatic Suspend Enable bit

`1` = USB module automatically suspends upon entry to Sleep mode. See the USUSPEND bit (U1PWRC<1>) in Register 10-5.

`0` = USB module does not automatically suspend upon entry to Sleep mode. Software must use the USUSPEND bit (U1PWRC<1>) to suspend the module, including the USB 48 MHz clock.

REGISTER 10-21: U1EP0-U1EP15: USB ENDPOINT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	LSPD	RETRYDIS	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as ‘0’

bit 7 **LSPD:** Low-Speed Direct Connection Enable bit (Host mode and U1EP0 only)

1 = Direct connection to a Low-Speed device enabled
0 = Direct connection to a Low-Speed device disabled; hub required with PRE_PID

bit 6 **RETRYDIS:** Retry Disable bit (Host mode and U1EP0 only)

1 = Retry NAKed transactions disabled
0 = Retry NAKed transactions enabled; retry done in hardware

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **EPCONDIS:** Bidirectional Endpoint Control bit

If EPTXEN = 1 and EPRXEN = 1:

1 = Disable Endpoint n from Control transfers; only TX and RX transfers allowed
0 = Enable Endpoint n for Control (SETUP) transfers; TX and RX transfers also allowed

Otherwise, this bit is ignored.

bit 3 **EPRXEN:** Endpoint Receive Enable bit

1 = Endpoint n receive is enabled
0 = Endpoint n receive is disabled

bit 2 **EPTXEN:** Endpoint Transmit Enable bit

1 = Endpoint n transmit is enabled
0 = Endpoint n transmit is disabled

bit 1 **EPSTALL:** Endpoint Stall Status bit

1 = Endpoint n was stalled
0 = Endpoint n was not stalled

bit 0 **EPHSHK:** Endpoint Handshake Enable bit

1 = Endpoint Handshake is enabled
0 = Endpoint Handshake is disabled (typically used for isochronous endpoints)

NOTES:

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

28.0 INSTRUCTION SET

The PIC32MX1XX/2XX family instruction set complies with the MIPS32® Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

Note: Refer to *“MIPS32® Architecture for Programmers Volume II: The MIPS32® Instruction Set”* at www.imgtec.com for more information.

TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	3.92	—	5	MHz	ECPLL, HSPLL, XTPLL, FRCPLL modes
OS51	FSYS	On-Chip VCO System Frequency	60	—	120	MHz	—
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	—	2	ms	—
OS53	DCLK	CLKO Stability[2] (Period Jitter or Cumulative)	-0.25	—	+0.25	%	Measured over 100 ms period

Note 1: These parameters are characterized, but not tested in manufacturing.

2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 40 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{40}{20}}} = \frac{D_{CLK}}{1.41}$$

TABLE 30-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Internal FRC Accuracy @ 8.00 MHz[1]						
F20b	FRC	-0.9	—	+0.9	%	—

Note 1: Frequency calibrated at 25°C and 3.3V. The TUN bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
LPRC @ 31.25 kHz[1]						
F21	LPRC	-15	—	+15	%	—

Note 1: Change of LPRC frequency as VDD changes.

FIGURE 30-12: SPIx MODULE SLAVE MODE (CKE = `0`) TIMING CHARACTERISTICS

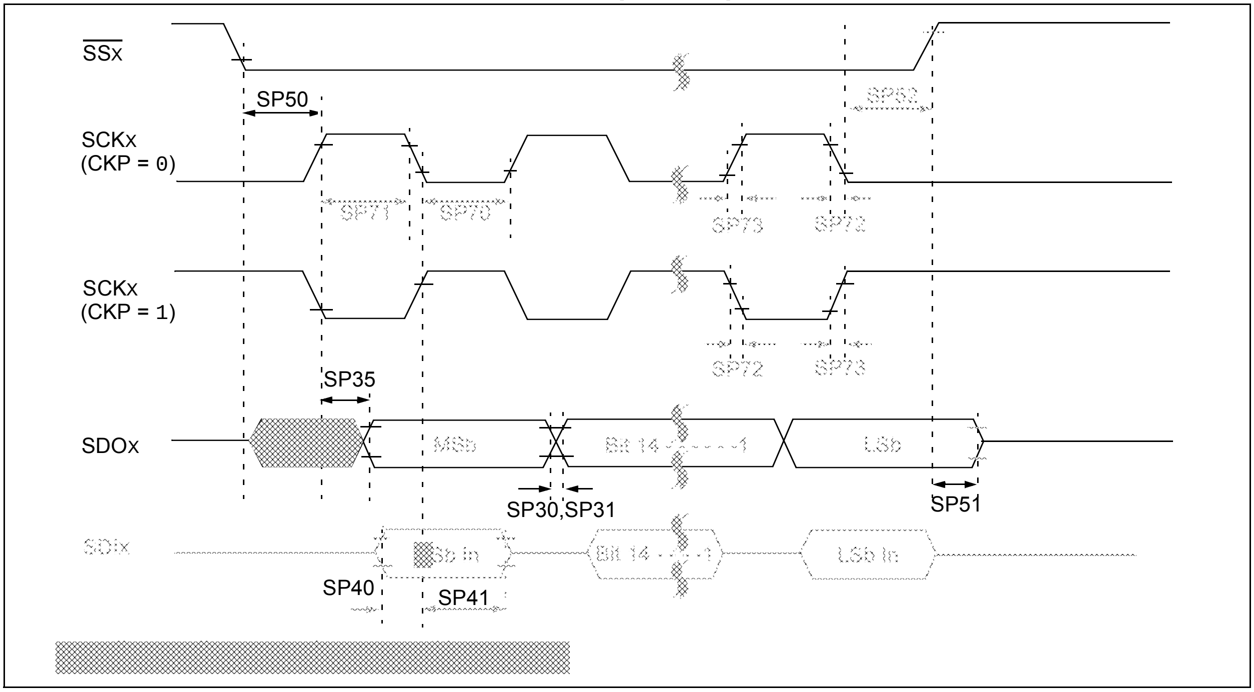


TABLE 30-30: SPIx MODULE SLAVE MODE (CKE = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance **(Note 3)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	Tsck + 20	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	1.3	—	µs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	µs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	PBCLK must operate at a minimum of 800 kHz
			400 kHz mode	0.6	—	µs	PBCLK must operate at a minimum of 3.2 MHz
			1 MHz mode **(Note 1)**	0.5	—	µs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 1)**	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 1)**	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 1)**	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250	—	ns	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	600	—	ns	

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

31.0 50 MHz ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices operating at 50 MHz.

The specifications for 50 MHz are identical to those shown in **Section 30.0 “Electrical Characteristics”**, with the exception of the parameters listed in this chapter.

Parameters in this chapter begin with the letter “M”, which denotes 50 MHz operation. For example, parameter DC29a in **Section 30.0 “Electrical Characteristics”**, is the up to 40 MHz operation equivalent for MDC29a.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family 50 MHz devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias	-40°C to +85°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS **(Note 3)**	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V **(Note 3)**	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V **(Note 3)**	-0.3V to +3.6V
Voltage on D+ or D- pin with respect to VUSB3V3	-0.3V to (VUSB3V3 + 0.3V)
Voltage on VBUS with respect to VSS	-0.3V to +5.5V
Maximum current out of VSS pin(s)	300 mA
Maximum current into VDD pin(s) **(Note 2)**	300 mA
Maximum output current sunk by any I/O pin	15 mA
Maximum output current sourced by any I/O pin	15 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports **(Note 2)**	200 mA

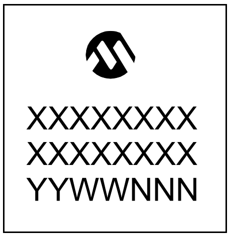
Note 1: Stresses above those listed under **“Absolute Maximum Ratings”** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

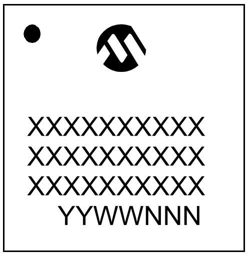
33.1 Package Marking Information (Continued)

36-Lead VTLA

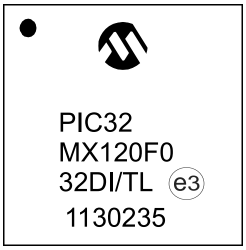


Example

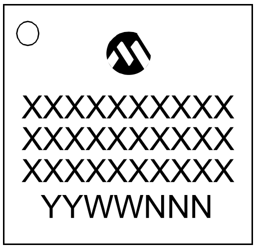
44-Lead VTLA



Example

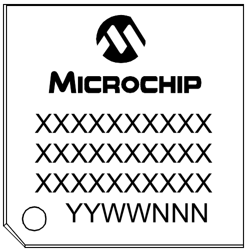


44-Lead QFN

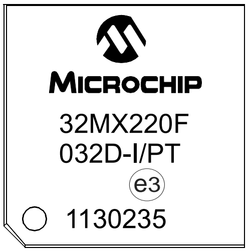


Example

44-Lead TQFP



Example

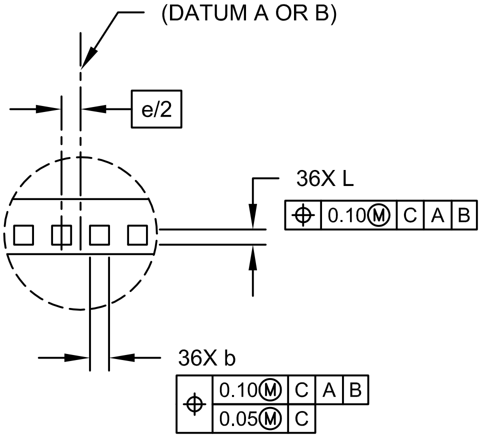


Legend:		
	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

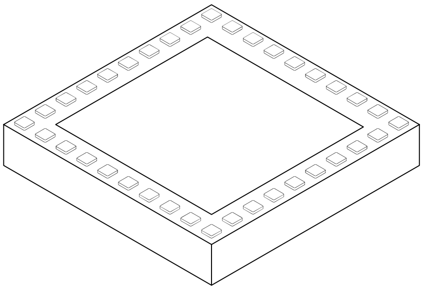
Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.
    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

APPENDIX A: REVISION HISTORY

Revision A (May 2011)

This is the initial released version of this document.

Revision B (October 2011)

The following two global changes are included in this revision:

- All packaging references to VLAP have been changed to VTLA throughout the document
- All references to VCORE have been removed
- All occurrences of the ASCL1, ASCL2, ASDA1, and ASDA2 pins have been removed
- V-temp temperature range (-40ºC to +105ºC) was added to all electrical specification tables

This revision includes the addition of the following devices:

- PIC32MX130F064B
- PIC32MX130F064C
- PIC32MX130F064D
- PIC32MX150F128B
- PIC32MX150F128C
- PIC32MX150F128D
- PIC32MX230F064B
- PIC32MX230F064C
- PIC32MX230F064D
- PIC32MX250F128B
- PIC32MX250F128C
- PIC32MX250F128D

Text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog”	Split the existing Features table into two: PIC32MX1XX General Purpose Family Features (Table 1) and PIC32MX2XX USB Family Features (Table 2). Added the SPDIP package reference (see Table 1, Table 2, and **“Pin Diagrams”**). Added the new devices to the applicable pin diagrams. Changed PGED2 to PGED1 on pin 35 of the 36-pin VTLA diagram for PIC32MX220F032C, PIC32MX220F016C, PIC32MX230F064C, and PIC32MX250F128C devices.
1.0 “Device Overview”	Added the SPDIP package reference and updated the pin number for AN12 for 44-pin QFN devices in the Pinout I/O Descriptions (see Table 1-1). Added the PGEC4/PGED4 pin pair and updated the C1INA-C1IND and C2INA-C2IND pin numbers for 28-pin SSOP/SPDIP/SOIC devices in the Pinout I/O Descriptions (see Table 1-1).
2.0 “Guidelines for Getting Started with 32-bit Microcontrollers”	Updated the Recommended Minimum Connection diagram (see Figure 2-1).